



### • General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

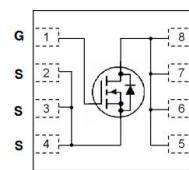
### • Features

- AEC-Q101 Qualified
- Low  $R_{DS(ON)}$  to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

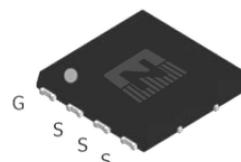
### • Application

- BLDC Motor driver
- DC-DC
- Battery protection

### • Product Summary



$V_{DS} = 60V$   
 $R_{DS(ON)} = 0.8m\Omega$   
 $I_D = 320A$



DFN8\*8



### • Ordering Information:

Part NO.	ZMSA007N06HG
Marking	ZMS007N06H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

### • Absolute Maximum Ratings ( $T_C=25^\circ C$ )

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	$V_{DS}$		60	V
Gate-Source Voltage <sup>①</sup>	$V_{GS}$		$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C=25^\circ C$	320	A
	$I_D$	$T_C=75^\circ C$	262	A
	$I_D$	$T_C=100^\circ C$	227	A
Pulsed Drain Current	$I_{DM}$	Pulsed; $t_p \leq 10 \mu s$ ; $T_{mb} = 25^\circ C$	960	A
Total Power Dissipation	$P_D$	$T_C=25^\circ C$	188	W
Total Power Dissipation	$P_D$	$T_A=25^\circ C$	4.3	W
Operating Junction Temperature	$T_J$		-55 to +175	°C
Storage Temperature	$T_{STG}$		-55 to +175	°C
Single Pulse Avalanche Energy	$E_{AS}$	$L=0.1mH$ , $V_{GS}=10V$ , $R_g=25\Omega$ ,	360	mJ
		$L=0.5mH$ , $V_{GS}=10V$ , $R_g=25\Omega$ ,	680	mJ
ESD Level (HBM)			CLASS 2	



## •Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	$R_{thJC}$		-	0.8	°C/W
Thermal resistance, junction-ambient <sup>(2)</sup>	$R_{thJA}$		-	35	°C/W
Soldering temperature	$T_{sold}$		-	260	°C

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	2	2.7	4	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{GS}=0V, V_{DS}= -60V$			1.0	$\mu A$
Gate- Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS} = 0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D= 40A$		0.8	1.1	$m\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = 5V, I_{SD} = 10A$		30		s
Diode Forward Voltage	$V_{FSD}$	$V_{GS} = 0V, I_{SD} = 40A$			1.3	V

## •Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	$C_{iss}$	$f = 1MHz, V_{DS}=25V$	-	11475	-	pF
Output capacitance	$C_{oss}$		-	6645	-	
Reverse transfer capacitance	$C_{rss}$		-	858	-	
Gate Resistance	$R_g$	$f = 1MHz$	-	1.6		$\Omega$
Total gate charge	$Q_g$	$V_{DD} = 15V, I_D = 20A, V_{GS} = 10V$	-	213	-	nC
Gate - Source charge	$Q_{gs}$		-	63	-	
Gate - Drain charge	$Q_{gd}$		-	43	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V, R_G = 3.3\Omega, I_D = 20A$	-	20	-	ns
Turn-ON Rise time	$t_r$		-	26	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	63	-	ns
Turn-Off Fall time	$t_f$		-	31	-	ns
Reverse Recovery Time	$t_{RR}$	$V_{DD}=20V, dI_S/dt = 100A/us, I_S=50A$	-	40	-	ns
Reverse Recovery Charge	$Q_{RR}$		-	38	-	nC



Fig.1 Gate-Charge Characteristics

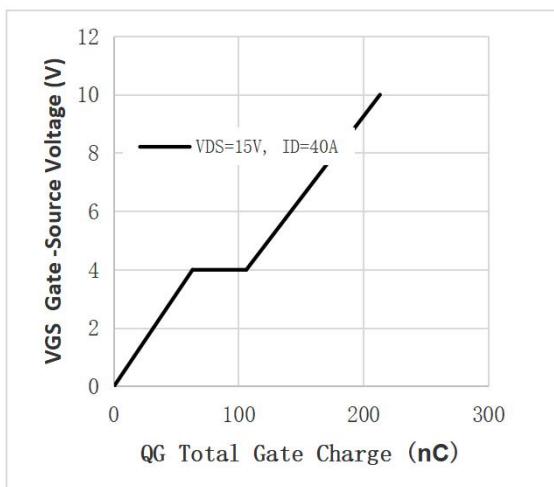


Fig.2 Capacitance Characteristics

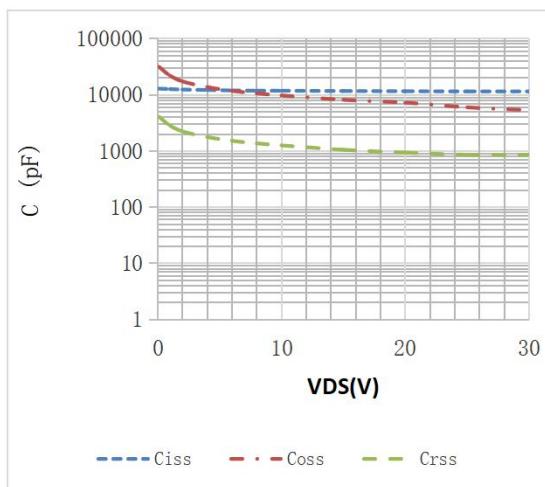


Fig.3 Power Dissipation

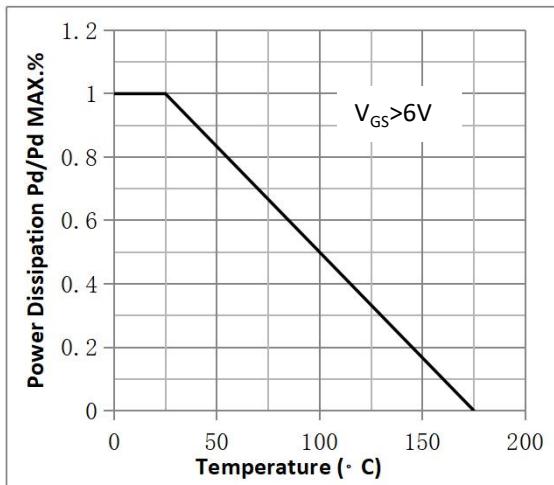


Fig.4 Typical output Characteristics

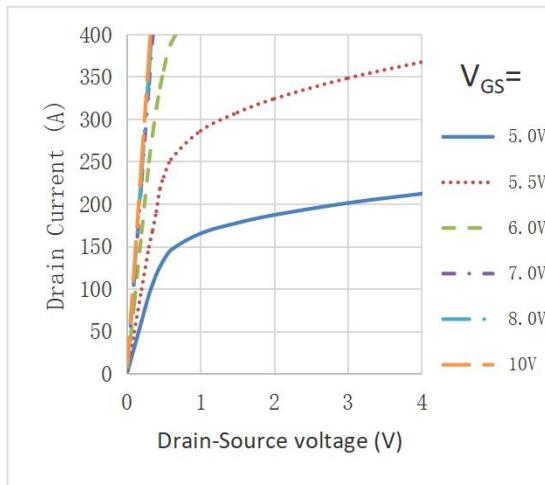


Fig.5 Threshold Voltage V.S Junction Temperature

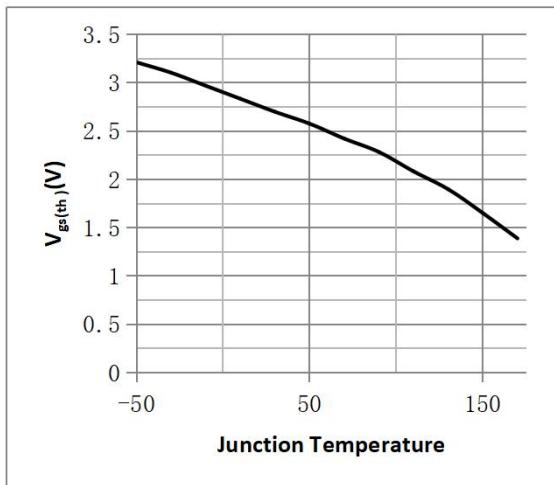


Fig.6 Resistance V.S Drain Current

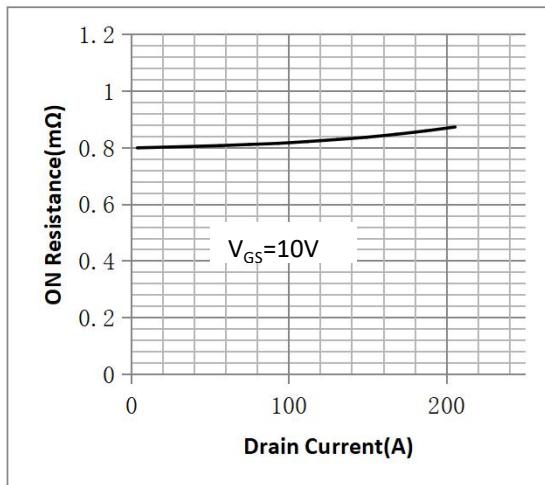




Fig.7 On-Resistance VS Gate Source Voltage

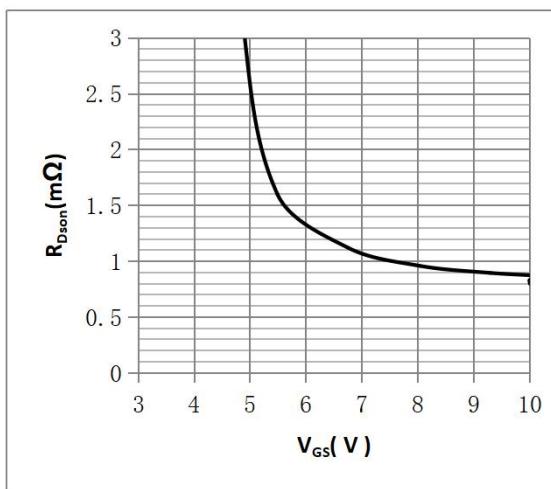


Fig.8 On-Resistance V.S Junction Temperature

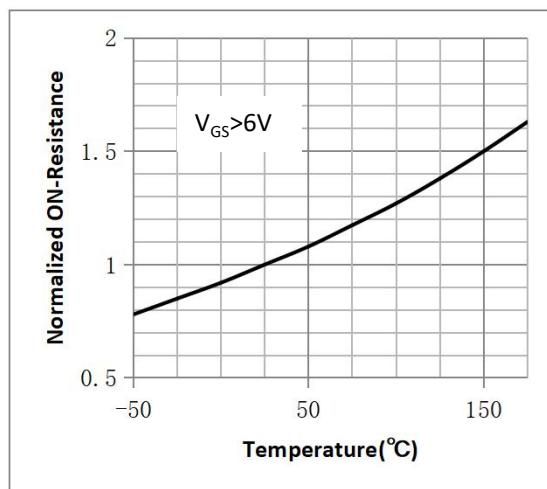


Figure 9. Diode Forward Voltage vs. Current

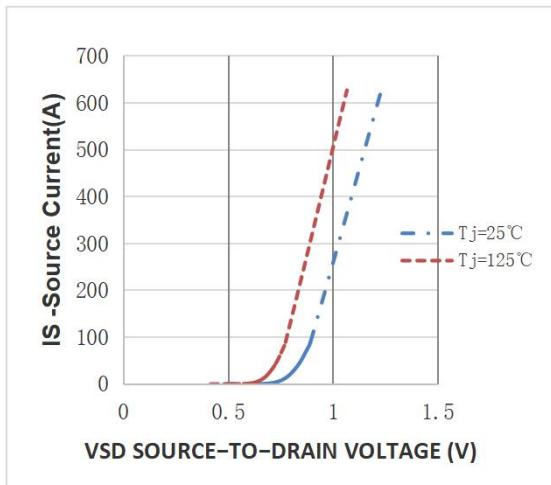


Figure 10. Transfer Characteristics

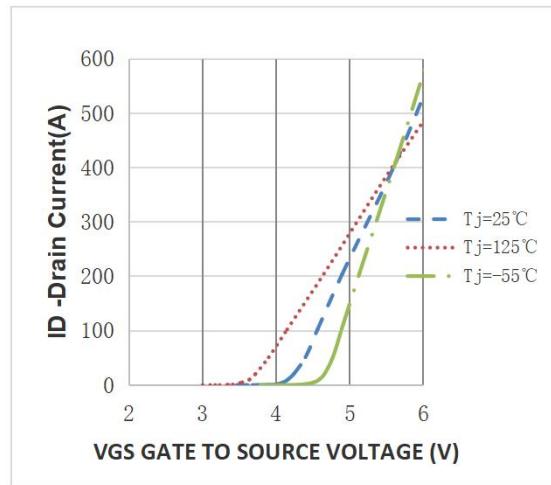
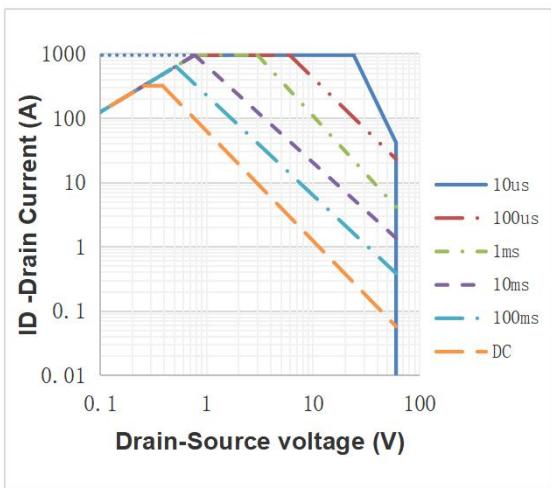
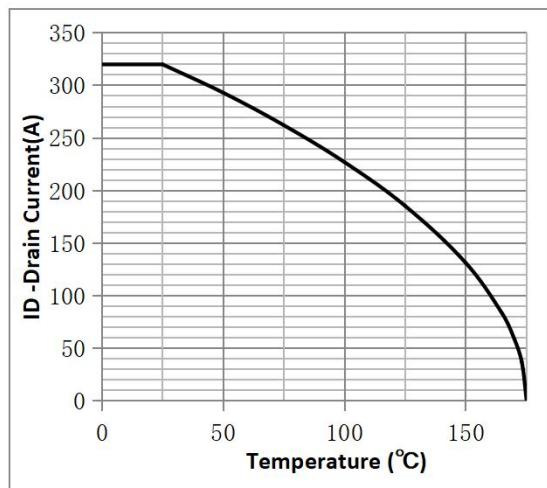
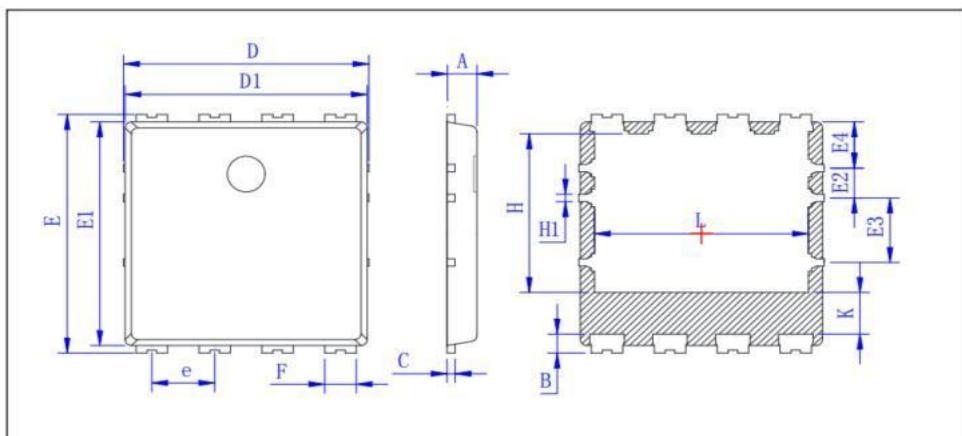


Fig.11 Safe Operating Area

Fig.12 ID vs. Junction Temperature<sup>③</sup>



## •DFN8\*8 Package Outline



Symbol	Min	Typ	Max
A	0.90	0.95	1.00
B	0.50	0.60	0.70
C	0.254 TYP		
D	7.70	7.80	7.90
D1	7.60	7.70	7.80
E	7.90	8.00	8.10
E1	7.40	7.50	7.60
E2	0.90	1.00	1.10
E3	2.06	2.16	2.26
E4	1.45	1.55	1.65
e	2.0 TYP		
F	1.00 TYP		
H	5.15	5.30	5.40
H1	0.20	0.25	0.35
L	6.60	6.80	6.90
K	1.20		

**Note:**

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175°C, t=1000 hours; For DC , the following test conditions can be passed: VGS=+20V/-10V, Tj=175°C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. VGS=10V.

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## Revision History

Version	Date	Change
A	2023.12.15	new